

L Number	Hits	Search Text	DB	Time stamp
1	26	"5473120"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:21
2	2	6319829.URPN.	USPAT	2003/03/01 08:53
3	16	("4074342" "4603023" "4617730" "4855871" "5073840" "5177594" "5313366" "5404044" "5473120" "5474458" "5484647" "5504035" "5571593" "5668059" "5866948" "6050832").PN.	USPAT	2003/03/01 08:53
4	6	4603023.URPN.	USPAT	2003/03/01 08:56
5	14	("2255184" "2396283" "2444997" "2813922" "3243760" "3351702" "3388212" "3490731" "3499219" "3734995" "3837074" "4090294" "4161817" "4195272").PN.	USPAT	2003/03/01 08:57
20	1	6243946.URPN.	USPAT	2003/03/01 08:59
21	22	("3683105" "4354311" "4382236" "4435740" "4467638" "4554033" "4588456" "4640981" "4642421" "4779340" "5187020" "5203075" "5421081" "5436411" "5473120" "5502889" "5528151" "5598139" "5662987" "5688584" "5699613" "5800650").PN.	USPAT	2003/03/01 09:00
22	4	("4328531" "4706167" "5196251" "5288952").PN.	USPAT	2003/03/01 09:05
23	1	5473120.pn. and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:31
24	1	5484647.pn. and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:26
25	0	6243946.pn. and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:33
26	7248	((carbon adj dioxide adj laser) (laser near irradiation)) with (laser near beam)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:37
27	6395	((carbon adj dioxide adj laser) (laser near irradiation)) near3(laser near beam)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:37
28	810	((((carbon adj dioxide adj laser) (laser near irradiation)) near3(laser near beam)) with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:37
29	391	((((carbon adj dioxide adj laser) (laser near irradiation)) near3(laser near beam)) with substrate) and (semiconductor chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:41
30	203	(((((carbon adj dioxide adj laser) (laser near irradiation)) near3(laser near beam)) with substrate) and (semiconductor chip die)) and contact	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:38
31	32	(((((carbon adj dioxide adj laser) (laser near irradiation)) near3(laser near beam)) with substrate) with ((through adj hole) vias)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:40
32	10	(((((carbon adj dioxide adj laser) (laser near irradiation)) near3(laser near beam)) with substrate) with ((through adj hole) vias)) and (semiconductor chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:41

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1	26	"5473120"	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT USPAT	2003/03/01 09:21 2003/03/01 08:53 2003/03/01 08:53
2	2	6319829.URPN.		
3	16	("4074342" "4603023" "4617730" "4855871" "5073840" "5177594" "5313366" "5404044" "5473120" "5474458" "5484647" "5504035" "5571593" "5668059" "5866948" "6050832").PN.		
4	6	4603023.URPN.		
5	14	("2255184" "2396283" "2444997" "2813922" "3243760" "3351702" "3388212" "3490731" "3499219" "3734995" "3837074" "4090294" "4161817" "4195272").PN.	USPAT USPAT	2003/03/01 08:56 2003/03/01 08:57
20	1	6243946.URPN.		
21	22	("3683105" "4354311" "4382236" "4435740" "4467638" "4554033" "4588456" "4640981" "4642421" "4779340" "5187020" "5203075" "5421081" "5436411" "5473120" "5502889" "5528151" "5598139" "5662987" "5688584" "5699613" "5800650").PN.	USPAT USPAT	2003/03/01 08:59 2003/03/01 09:00
22	4	("4328531" "4706167" "5196251" "5288952").PN.	USPAT	2003/03/01 09:05
23	1	5473120.pn. and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:31
24	1	5484647.pn. and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:26
25	0	6243946.pn. and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:33
26	7248	((carbon adj dioxide adj laser) (laser near irradiation)) with (laser near beam)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:37
27	6395	((carbon adj dioxide adj laser) (laser near irradiation)) near3(laser near beam)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:37
28	810	((((carbon adj dioxide adj laser) (laser near irradiation)) near3(laser near beam)) with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:37
29	391	(((((carbon adj dioxide adj laser) (laser near irradiation)) near3(laser near beam)) with substrate) and (semiconductor chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:41
30	203	(((((carbon adj dioxide adj laser) (laser near irradiation)) near3(laser near beam)) with substrate) and (semiconductor chip die)) and contact	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:38
31	32	((((carbon adj dioxide adj laser) (laser near irradiation)) near3(laser near beam)) with substrate) with ((through adj hole) vias)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:40
32	10	(((((carbon adj dioxide adj laser) (laser near irradiation)) near3(laser near beam)) with substrate) with ((through adj hole) vias)) and (semiconductor chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 09:49

33	2	5263243.pn. and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 10:04
34	15	"6294837"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 10:05
35	43	(US-6424048-\$ or US-6373273-\$ or US-6235554-\$ or US-6130111-\$ or US-6114240-\$ or US-6110825-\$ or US-5599744-\$ or US-4978639-\$ or US-6400172-\$ or US-6294837-\$ or US-6504105-\$ or US-6468813-\$ or US-6462282-\$ or US-5717247-\$ or US-5675889-\$ or US-5493096-\$ or US-6211487-\$ or US-6203652-\$ or US-6319829-\$ or US-6329610-\$ or US-6340841-\$ or US-6392164-\$ or US-6440641-\$ or US-6452117-\$ or US-6492600-\$ or US-6525275-\$).did. or (US-5484647-\$ or US-5473120-\$ or US-5474458-\$ or US-5404044-\$ or US-4603023-\$ or US-6303881-\$ or US-6281448-\$ or US-6270607-\$ or US-6243946-\$ or US-6204456-\$ or US-6201194-\$ or US-6050832-\$ or US-6010769-\$ or US-5883335-\$ or US-5263243-\$ or US-6498503-\$).did. or (US-6039889-\$).did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 12:04
94	4	("4328531" "4706167" "5196251" "5288952").PN.	USPAT	2003/03/01 12:14
95	24	5473120.URPN.	USPAT	2003/03/01 12:14
96	8	6201194.URPN.	USPAT	2003/03/01 12:17
97	4	("4328531" "4706167" "5196251" "5288952").PN.	USPAT	2003/03/01 12:22
112	22	("3683105" "4354311" "4382236" "4435740" "4467638" "4554033" "4588456" "4640981" "4642421" "4779340" "5187020" "5203075" "5421081" "5436411" "5473120" "5502889" "5528151" "5598139" "5662987" "5688584" "5699613" "5800650").PN.	USPAT	2003/03/01 12:25
127	52	("4795977" "5046239" "5172050" "5225037" "5289631" "5341564" "5495667" "5500605" "5519332" "5592736" "5625298" "5629837" "5691041" "5716218" "5796264" "5815000" "5834945" "5869974" "5894161" "5915977" "5931685" "5952840" "5982185" "6005288" "6016060" "6018249" "6025730" "6025731" "6040239" "6040702" "6046598" "6060891" "6068669" "6072321" "6072326" "6078186" "6091252" "6114864" "6127736" "6188230" "6222280" "6265245" "6275052" "6285203" "6294837" "6300782" "6310484" "6362637" "6407570" "6414506" "6437451" "6437591").PN.	USPAT	2003/03/01 12:31
128	27	5046239.URPN.	USPAT	2003/03/01 12:37

131	33	("5046239" "5063177" "5172050" "5229647" "5236551" "5249450" "5420520" "5426072" "5483741" "5487999" "5528080" "5541525" "5578526" "5592736" "5607818" "5633122" "5634267" "5674785" "5686317" "5716218" "5781022" "5783461" "5801452" "5815000" "5834945" "5869974" "5878485" "5896036" "5915977" "5929647" "5931685" "5962921" "6013948").PN.	USPAT	2003/03/01 12:38
132	80	substrate with ((through adj hole) vias opening) with laser with (drill drilling drilled) with (conductive contact)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/01 12:44
133	2	6119338.URPN.	USPAT	2003/03/01 12:50
134	13	("4915983" "5092032" "5293025" "5347712" "5451721" "5481795" "5512514" "5558928" "5568682" "5640761" "5744758" "5925206" "5960538").PN.	USPAT	2003/03/01 12:51
135	44	5481795.URPN.	USPAT	2003/03/01 12:53
136	9	("3330695" "3672986" "4595606" "4664962" "5232765" "5326636" "5346750" "5481795" "5652042").PN.	USPAT	2003/03/01 12:59
141	4	5780143.URPN.	USPAT	2003/03/01 13:00
142	25	4258468.URPN.	USPAT	2003/03/01 13:06